



Layer Stack Up Detail for: ISE_MCS_DSM_E2.PcbDoc			
Layer Name	Material	Copper Thickness	Dielectric Material
Top Solder Mask	C615D		Solder Resist
Top Layer	C61L	2.8mil	FR-4 High Tg
Middle Layer 1	C61D	2.8mil	FR-4 High Tg
Middle Layer 2	C62D	2.8mil	FR-4 High Tg
Bottom Layer	C61L	2.8mil	FR-4 High Tg
Bottom Solder Mask	C615D		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)

787.4MM X 255.9MM

Number of Layers : 4

MIN. TRACK WIDTH: 8 MIL

MIN. CLEARANCE: 8 MIL

MIN. VIA PAD SIZE: 32 MIL

MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL

PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

VAS ARE TEXTED

IT IS NOT IMPEDANCE CONTROLLED BOARD

MATERIAL:

☐ FR-408 ☒ FR-4 High Tg ☐ OTHER

THICKNESS: ☒ 62 MIL (1.6mm) +/-10% ☐ OTHER

TOLERANCE: ☒ ANSI PC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

BOW & TWIST: ☒ ANSI PC-6012 TYPE 3 CLASS 2

☐ OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER: ☐ 1.4MIL (1oz) ☐ 2MIL (1.4oz) ☒ 2.8MIL (2oz)

INNER SIGNAL: ☐ 1.4MIL (1oz) ☒ 2.8MIL (2oz) ☐ N/A

DRILLING:

REFERENCE: ☒ AS SHOWN ☒ NC_DRILL FILES

PTH MIN COPPER THICKNESS: ☒ 1MIL ☐ OTHER

BOARD FINISH:

SILKSCREEN: ☒ TOP ☒ BOTTOM

SILKSCREEN COLOR: ☒ WHITE ☐ OTHER

SOLDER RESIST COLOR:

☒ GREEN ☐ BLUE ☐ OTHER

SURFACE FINISH: ☒ IMMERSION GOLD (ENIG) ☐ ENERPIG

☐ MM. TIN/SILVER OR EQUIV ☐ OTHER

ARRAY/PANEL:

☐ CUT AND TRIM PER MECH LAYER 1

☐ N.C. ROUTE ☒ V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

☒ ANSI PC-A-600F CLASS -> ☐ 1 ☒ 2 ☐ 3

☒ UL 94V-0 ☒ RoHS ☐ OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION: ☐ YES

BARE BOARD ELEC. TEST: ☐ NONE ☒ REQUIRED ☐ PER ORDER

MANUFACTURER'S UL: ☐ RAIL ☐ METAL ☒ SILK



PROJECT TITLE: ISE_MCS_DSM_E2	
DESIGNED FOR: Public Release	
FILE NAME: ISE_MCS_DSM_E2.PcbDoc	
ENGINEER: Narayananasamy Navaneeth	LAYOUT BY: Vamsi T
SCALE: 1.00	
ALTIM DESIGER VERSION: 10.0.0.27009	

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-00171	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Multilayer			
PLOT NAME = Multilayer Composite Print	GENERATED : 7/22/2014 11:23:51 AM	TEXAS INSTRUMENTS	

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